

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3	(clean\$3 and termination and material and gas and pressure and hydrogen and clean\$3).clm.	US-PGPUB; USPAT	OR	ON	2009/02/26 16:48
L2	2	(clean\$3 and termination and material and gas and pressure and hydrogen and clean\$3 and deposition).clm.	US-PGPUB; USPAT	OR	ON	2009/02/26 16:49
L3	1	(clean\$3 and termination and material and gas and pressure and hydrogen and clean\$3 and deposition and fluoride).clm.	US-PGPUB; USPAT	OR	ON	2009/02/26 16:50
L4	1	(clean\$3 and termination and material and gas and pressure and hydrogen and clean\$3 and deposition and fluoride and temperature).clm.	US-PGPUB; USPAT	OR	ON	2009/02/26 16:52
S1	11	("20040043570" "20040153612" "20050091456" "20050108483" "4752505" "4845043" "5620559" "5805879" "6024045" "6336463" "6350322" "6492283" "6647301" "6690040" "6735666").PN.	USPAT	OR	ON	2008/01/05 16:40
S2	322	"hydrogen termination"	USPAT	OR	ON	2007/03/29 12:31
S3	218	"hydrogen termination" and nitrogen	USPAT	OR	ON	2007/09/05 10:45
S4	48	"hydrogen termination" and nitrogen with temperature	USPAT	OR	ON	2007/03/29 12:32

S5	30	("2394930" "3895127" "4056642" "4292343" "4343830" "4436761" "4544571" "4645683" "4766006" "5135775" "5281546" "5576071" "5587205" "5780115" "5939763" "5950107" "5990013" "5993916" "6090217" "6107192" "6200866" "6296715" "6297539" "6503330" "6551399" "6649543" "6727148" "6744104" "6800830").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/29 15:22
S6	28	"6613695"	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/29 16:59
S10	23	"6613695"	USPAT	OR	ON	2007/03/29 18:53
S11	12	09/944734	US-PGPUB; USPAT	OR	ON	2007/03/30 11:46
S12	23	("2394930" "3895127" "4056642" "4292343" "4343830" "4436761" "4544571" "4645683" "4766006" "5135775" "5281546" "5576071" "5587205" "5780115" "5939763" "5950107" "5990013" "5993916" "6090217" "6107192" "6200866" "6296715").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/29 19:46
S13	12	"6350322"	USPAT	OR	ON	2007/03/30 11:33
S14	4	"hydrogen termination" and preheat	USPAT	OR	ON	2007/09/05 10:45
S15	9	"hydrogen termination" and preheat\$3	USPAT	OR	ON	2007/09/05 10:45

S16	1	10/675575	US-PGPUB; USPAT	OR	ON	2007/09/12 14:23
S17	30567	"134".clas.	USPAT	OR	ON	2008/01/05 16:40
S18	10654	(substrate circuit wafer surface) with (fabricat \$4 clean\$4 wash\$4 rins \$4 process\$4 treat\$4) and (heat\$3) with (gas) with (NH3 or nitrogen fluoride or "NH.sub.3")	USPAT	OR	ON	2008/01/05 16:45
S20	7035	(substrate circuit wafer surface) near3 (fabricat \$4 clean\$4 wash\$4 rins \$4 process\$4 treat\$4) and (heat\$3) with (gas) with (NH3 or nitrogen fluoride or "NH.sub.3")	USPAT	OR	ON	2008/01/05 16:46
S21	29	(substrate circuit wafer surface) near3 (fabricat \$4 clean\$4 wash\$4 rins \$4 process\$4 treat\$4) and (heat\$3) with (gas) with (NH3 or nitrogen fluoride or "NH.sub.3") with "800"	USPAT	OR	ON	2008/01/05 16:46
S22	437	(substrate circuit wafer surface) near3 (fabricat \$4 clean\$4 wash\$4 rins \$4 process\$4 treat\$4) and (heat\$3) with (gas) with (NH3 or nitrogen adj fluoride or "NH.sub.3")	USPAT	OR	ON	2008/01/05 16:47
S23	16	(substrate circuit wafer surface) near3 (fabricat \$4 clean\$4 wash\$4 rins \$4 process\$4 treat\$4) and (heat\$3) with (gas) with (NH3 or nitrogen adj fluoride or "NH.sub.3") with ("500" "600" "700" "800")	USPAT	OR	ON	2008/01/05 16:48

S24	20	(substrate circuit wafer surface) near3 (fabricat\$4 clean\$4 wash\$4 rins\$4 process\$4 treat\$4) and (heat\$3) with (gas) with (NF3 or nitrogen adj fluoride or "NF.sub.3") with ("500" "600" "700" "800")	USPAT	OR	ON	2008/01/05 16:48
S25	630	hydrogen adj termination	US-PGPUB; USPAT	OR	ON	2008/06/11 14:58
S26	82	hydrogen adj termination and ("NF.sub.3" or nitrogen adj fluoride)	US-PGPUB; USPAT	OR	ON	2008/06/11 14:59
S27	24	hydrogen adj termination and ("NF.sub.3" or nitrogen adj fluoride) same pressure	US-PGPUB; USPAT	OR	ON	2008/06/11 14:59
S28	2	"7415666"	USPAT	OR	ON	2008/09/02 17:23
S29	1	"6960975"	USPAT	OR	ON	2008/09/03 11:13
S30	397	("NF.sub.3" or nitrogen adj fluoride) with torr	US-PGPUB; USPAT	OR	ON	2008/09/03 11:17
S31	307	("NF.sub.3" or nitrogen adj fluoride) same (surface contaminants) same (torr)	US-PGPUB; USPAT	OR	ON	2008/09/03 11:21
S32	307	("NF.sub.3" or nitrogen adj fluoride) same (surface contaminants) same (torr)	US-PGPUB; USPAT	OR	ON	2008/09/03 11:21
S33	115	hydrogen adj bake	USPAT	OR	ON	2009/02/20 17:06
S34	31	hydrogen adj bake and ("NF.sub.3")	USPAT	OR	ON	2009/02/20 17:06
S35	70	hydrogen adj bake and ("NF.sub.3")	US-PGPUB; USPAT	OR	ON	2009/02/20 18:24
S36	39	S35 not S34	US-PGPUB; USPAT	OR	ON	2009/02/20 18:24
S37	0	(hydrogen or "H.sub.2") with reduc\$5 same (temperature) and "NF.sub.3"	USPAT	OR	ON	2009/02/24 17:31

S38	328	(hydrogen or "H.sub.2") with reduc\$5 same (temperature) and "NF.sub.3"	USPAT	OR	ON	2009/02/24 17:31
S39	307	(hydrogen or "H.sub.2") with reduc\$5 same (temperature) and "NF.sub.3" and (semiconductor substrate wafer)	USPAT	OR	ON	2009/02/26 13:00
S40	138	(hydrogen or "H.sub.2") with gas with reduc\$5 same (temperature) and "NF.sub.3" and (semiconductor substrate wafer)	USPAT	OR	ON	2009/02/26 13:02
S41	326	(hydrogen or "H.sub.2") with gas with reduc\$5 and "NF.sub.3" and (semiconductor substrate wafer)	USPAT	OR	ON	2009/02/26 13:02
S42	659	(hydrogen or "H.sub.2") with gas with reduc\$5 and "NF.sub.3" and (semiconductor substrate wafer)	US-PGPUB; USPAT	OR	ON	2009/02/26 13:11
S43	78	(hydrogen or "H.sub.2") with gas with reduc\$5 with temperature and "NF.sub.3" and (semiconductor substrate wafer)	US-PGPUB; USPAT	OR	ON	2009/02/26 13:12
S44	0	((nitrogen adj fluoride or "NF.sub.3") and clean\$3 and termination and hot adj plate and material). clm.	US-PGPUB; USPAT	OR	ON	2009/02/26 14:53
S45	0	(clean\$3 and termination and hot adj plate and material). clm.	US-PGPUB; USPAT	OR	ON	2009/02/26 14:53

S46	0	(clean\$3 and termination and (hot adj plate) and material).clm.	US-PGPUB; USPAT	OR	ON	2009/02/26 14:54
S47	182	(clean\$3 and termination and material).clm.	US-PGPUB; USPAT	OR	ON	2009/02/26 14:54
S48	0	(clean\$3 and termination and material and hot and plate).clm.	US-PGPUB; USPAT	OR	ON	2009/02/26 14:54
S49	22	(clean\$3 and termination and material and gas and pressure).clm.	US-PGPUB; USPAT	OR	ON	2009/02/26 14:54
S50	3	(clean\$3 and termination and material and gas and pressure and hydrogen).clm.	US-PGPUB; USPAT	OR	ON	2009/02/26 14:55

2/ 26/ 2009 6:19:21 PM

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